Low V_{CE(sat)} Transistor, PNP, 12 V, 1.0 A, SOT-563 Package

ON Semiconductor's e^2 PowerEdge family of low $V_{CE(sat)}$ transistors are miniature surface mount devices featuring ultra low saturation voltage ($V_{CE(sat)}$) and high current gain capability. These are designed for use in low voltage, high speed switching applications where affordable efficient energy control is important.

Typical application are DC-DC converters and power management in portable and battery powered products such as cellular and cordless phones, PDAs, computers, printers, digital cameras and MP3 players. Other applications are low voltage motor controls in mass storage products such as disc drives and tape drives. In the automotive industry they can be used in air bag deployment and in the instrument cluster. The high current gain allows e²PowerEdge devices to be driven directly from PMU's control outputs, and the Linear Gain (Beta) makes them ideal components in analog amplifiers.

Features

- High Current Capability (1 A)
- High Power Handling (Up to 650 mW)
- Low V_{CE(s)} (150 mV Typical @ 500 mA)
- Small Size
- This is a Pb-Free Device

Benefits

- High Specific Current and Power Capability Reduces Required PCB Area
- · Reduced Parasitic Losses Increases Battery Life

MAXIMUM RATINGS $(T_A = 25^{\circ}C)$

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Rating	Symbol	Max	Unit
Collector-Emitter Voltage	V _{CEO}	-12	Vdc
Collector-Base Voltage	V _{CBO}	-12	Vdc
Emitter-Base Voltage	V _{EBO}	-5.0	Vdc
Collector Current – Continuous – Peak	I _C I _{CM}	-1.0 -2.0	Adc
Electrostatic Discharge	ESD	HBM Cla MM Clas	

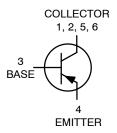
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.



ON Semiconductor®

http://onsemi.com

12 VOLTS, 1.0 AMPS PNP LOW $V_{CE(sat)}$ TRANSISTOR EQUIVALENT $R_{DS(on)}$ 300 m Ω





SOT-563 CASE 463A STYLE 4

DEVICE MARKING



VE = Specific Device Code

M = Month Code

= Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping [†]
NSS12100XV6T1G	SOT-563 (Pb-Free)	

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation T _A = 25°C	P _D (Note 1)	500	mW
Derate above 25°C		4.0	mW/°C
Thermal Resistance, Junction-to-Ambient	R _{θJA} (Note 1)	250	°C/W
Total Device Dissipation T _A = 25°C	P _D (Note 2)	650	mW
Derate above 25°C		5.2	mW/°C
Thermal Resistance, Junction-to-Ambient	R _{θJA} (Note 2)	192	°C/W
Thermal Resistance, Junction-to-Lead 6	$R_{ hetaJL}$	105	°C/W
Total Device Dissipation (Single Pulse < 10 sec.)	P _D Single	1.0	W
Junction and Storage Temperature Range	T _J , T _{stg}	-55 to +150	°C

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS					
Collector – Emitter Breakdown Voltage, (I _C = -10 mAdc, I _B = 0)	V _{(BR)CEO}	-12	-	-	Vdc
Collector - Base Breakdown Voltage, (I _C = -0.1 mAdc, I _E = 0)	V _{(BR)CBO}	-12	-	-	Vdc
Emitter – Base Breakdown Voltage, ($I_E = -0.1 \text{ mAdc}$, $I_C = 0$)	V _{(BR)EBO}	-5.0	-	-	Vdc
Collector Cutoff Current, (V _{CB} = -12 Vdc, I _E = 0)	I _{CBO}	-	-0.02	-0.1	μAdc
Emitter Cutoff Current, (V _{CES} = -5.0 Vdc, I _E = 0)	I _{EBO}	-	-0.03	-0.1	μAdc
ON CHARACTERISTICS					

DC Current Gain (Note 3) $(I_C = -10 \text{ mA}, V_{CE} = -2.0 \text{ V})$ $(I_C = -500 \text{ mA}, V_{CE} = -2.0 \text{ V})$ $(I_C = -1.0 \text{ A}, V_{CE} = -2.0 \text{ V})$	h _{FE}	200 100 90	- - -	- - -	
Collector – Emitter Saturation Voltage (Note 3) ($I_C = -0.05 \text{ A}, I_B = -0.005 \text{ A}$) (Note 4) ($I_C = -0.1 \text{ A}, I_B = -0.002 \text{ A}$) ($I_C = -0.1 \text{ A}, I_B = -0.010 \text{ A}$) ($I_C = -0.5 \text{ A}, I_B = -0.050 \text{ A}$) ($I_C = -1.0 \text{ A}, I_B = -0.100 \text{ A}$)	V _{CE(sat)}	- - - -	-0.030 -0.080 -0.050 -0.200 -0.400	-0.040 -0.100 -0.060 -0.225 -0.440	V
Base – Emitter Saturation Voltage (Note 3) (I _C = -1.0 A, I _B = -0.01 A)	V _{BE(sat)}	-	0.95	-1.15	V
Base – Emitter Turn–on Voltage (Note 3) (I _C = -2.0 A, V _{CE} = -3.0 V)	V _{BE(on)}	ı	-1.05	-1.15	V
Input Capacitance (V _{EB} = -0.5 V, f = 1.0 MHz)	Cibo	-		50	pF
Output Capacitance (V _{CB} = -3.0 V, f = 1.0 MHz)	Cobo	-		20	pF

FR-4 @ 100 mm², 1 oz copper traces.
 FR-4 @ 500 mm², 1 oz copper traces.
 Pulsed Condition: Pulse Width = 300 μsec, Duty Cycle ≤ 2%.
 Guaranteed by design but not tested.

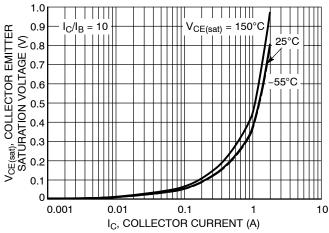


Figure 1. Collector Emitter Saturation Voltage vs.
Collector Current

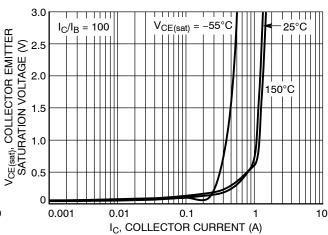


Figure 2. Collector Emitter Saturation Voltage vs.
Collector Current

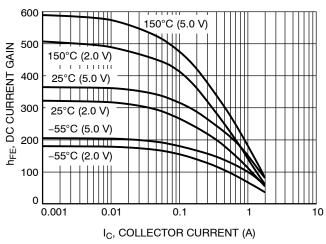


Figure 3. DC Current Gain vs. Collector Current

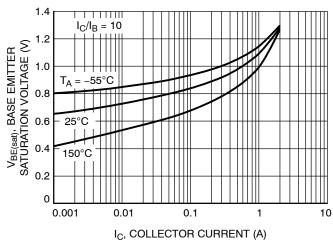


Figure 4. Base Emitter Saturation Voltage vs.
Collector Current

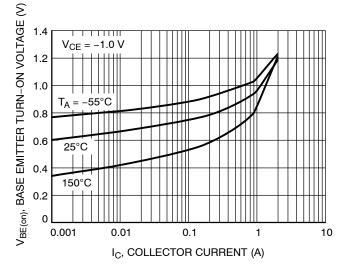


Figure 5. Base Emitter Turn-On Voltage vs. Collector Current

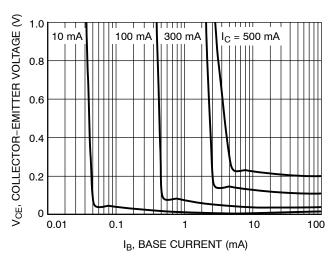
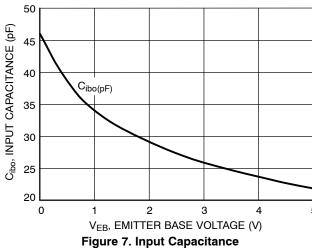


Figure 6. Saturation Region



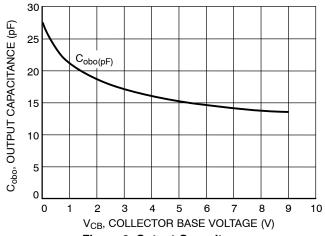


Figure 8. Output Capacitance



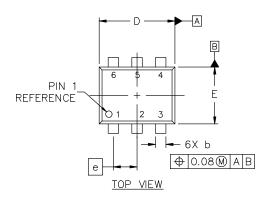


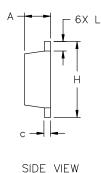
SOT-563-6 1.60x1.20x0.55, 0.50P CASE 463A **ISSUE J**

DATE 15 FEB 2024

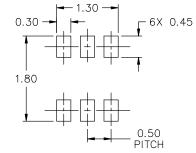
NOTES:

- DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5-2018.
- ALL DIMENSION ARE IN MILLIMETERS.
- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.





DIM	MILLIMETERS		:RS
ויונע	MIN.	N□M.	MAX.
А	0.50	0.55	0.60
b	0.17	0.22	0.27
C	0.08	0.13	0.18
D	1.50	1.60	1.70
E	1.10	1.20	1.30
е	0.50 BSC		
Н	1.50	1.60	1.70
L	0.10	0.20	0.30



STYLE 1:	STYLE 2:	STYLE 3:
PIN 1. EMITTER 1	PIN 1. EMITTER 1	PIN 1. CATHODE 1
2. BASE 1	2. EMITTER 2	2. CATHODE 1
3. COLLECTOR 2	3. BASE 2	3. ANODE/ANODE 2
4. EMITTER 2	4. COLLECTOR 2	4. CATHODE 2
5. BASE 2	5. BASE 1	5. CATHODE 2
6. COLLECTOR 1	6. COLLECTOR 1	6. AN□DE/AN□DE 1

STYLE 6: PIN 1. CATHODE 2. ANODE

SOT-563-6 1.60x1.20x0.55, 0.50P

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3. CATHODE 4. CATHODE 5. CATHODE

RECOMMENDED	MOLINITING	FOOTDRINIT*
RECOMMENDED	MOUNTING	FUU IPRIN I*

FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

STYLE 7:	STYLE 9: PIN 1. SDURCE 1 2. GATE 1 3. DRAIN 2 4. SDURCE 2 5. GATE 2 6. DRAIN 1
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STYLE 5:

PIN 1. CATHODE

2. CATHODE

3. ANDDE 4. ANDDE 5. CATHODE

GENERIC MARKING DIAGRAM*



XX = Specific Device Code M = Month Code

= Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "=", may or may not be present. Some products may not follow the Generic Marking.

STYLE 10:	STYLE 11:
PIN 1. CATHODE 1	PIN 1. EMITTER 2
2. N/C	2. BASE 2
3. CATHODE 2	3. COLLECTOR 1
4. AN□DE 2	4. EMITTER 1
5. N/C	5. BASE 1
6. AN□DE 1	6. COLLECTOR 2

STYLE 4: PIN 1. COLLECTOR

2. COLLECTOR

3. BASE 4. EMITTER 5. COLLECTOR

COLLECTOR

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DESCRIPTION:

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